

DIGITAL **COMPONENT SENSOR** DEVELOPMENT TOOLS

Many of our digital sensor products are available in low power and small form factors. They are suited for wearable and miniature devices that are used to collect and share critical data for health monitoring, fitness, air quality, aerospace, battery powered, and related applications. To increase knowledge sharing and reduce time to market, we have teamed with semiconductor manufacturers to design and provide plug and play tools for Xplained Pro Sensor Hub, MicroChip PicTail, and Digilent Pmod™ based development platforms. In addition, we offer several wireless demo/development tools to help engineers quickly achieve their design objectives with wireless applications. These tools are supported with software/firmware drivers, documentation, and graphic user interfaces to make the development process easy.



WIRELESS DEMO AND DEVELOPMENT KITS



MEAS Environmental Sensor Tag

Humidity, Temperature, Pressure

- 0 100% RH
- 20°C to 85°C
- 300 to 1.200 mbar

Standard 2.4 GHz wireless communication

iOS 70+ Application Android™ 4.3+

Туре

Specifications

Communication



MEAS Wireless M5600 Series

Pressure

- 50 15K psi
- Type G/S/C

Standard 2.4 GHz wireless communication

Android™ 4.3+



MEAS Wireless U5600 Series

Pressure

- 2 10K psi • Type G/S/C/A

Standard 2.4 GHz wireless communication

Android™ 4.3+



MEAS Wireless FX1951

Force

• 0 - 50 lbf

Standard 2.4 GHz wireless communication

iOS 70+ Android™ 4.3+

PICTAIL PLUS



MEAS HTU21D(F), MS5637, MS8607,

Type

TE Demo

Specifications

Humidity. Temperature, Pressure

- 0 100% RH
 - -20°C to 85°C
- 300 to 1,200 mbar

PicTail Plus

Partner Board Microchip Explorer 16

^{*}Temperature System Sensor (TSYS) Series

DIGITAL COMPONENT SENSOR DEVELOPMENT TOOLS



PERIPHERAL MODULES

Digilent Pmod™







MEAS MS8607







MEAS HTU21D(I	F

Humidity

Specifications • 0 to 100% RH • -40 to 125°C

• 3.3 to 5.5 V

Accuracy ±3% RH

Comm. Interface Board

Туре

Connections Compatibility 120

6 x 2 x 0.1" header input & output

Development systems compatible with Digilent Pmod™ connections

MEAS MS5637

Pressure

• -40 to 85°C

• 15 to 36 V

6 x 2 x 0.1" header

Development systems

input & output

compatible with

Digilent Pmod™

connections

±2 mbar

I²C

Pressure. Temperature, Humidity

• 10 to 2,000 mbar • 10 to 2,000 mmar

• -40 to 85°C • 0 to 100% RH

• 1.5 to 3.6 V

±3% RH, ±2 mbar, ±1.0°C

120

6 x 2 x 0.1" header input & output

Development systems compatible with Digilent Pmod™ connections

MEAS TSYSO1*

Temperature

• -40 to 125°C

• 2.2 to 3.6 V

±0.1°C

6 x 2 x 0.1" header input & output

Development systems compatible with Digilent Pmod™ connections

MEAS TSYSO2D*

Temperature

• -40 to 125°C

• 1.5 to 3.6 V

±0.2°C

1²C

6 x 2 x 0.1" header input & output

Development systems compatible with Digilent Pmod™ connections

MEAS KMA36(A)

Angular Position

• 0 to 360°

• -25 to 85°C

• 2.9 to 6.0 V

±0.1°

120

6 x 2 x 0.1" header input & output

Development systems compatible with Digilent Pmod™ connections

WING BOARDS















MEAS HTU21D(F)

Туре Humidity

Specifications

Accuracy

Comm. Interface

Board

Connections Compatibility

• 0 to 100% RH

• -40°C to 125°C

• 3.3 to 5.5 V

±3% RH

10 x 2 x 0.1" header input & output

Configured to operate with the Xplained Pro development platform

Pressure

• 10 to 2,000 mbar

MEAS MS5637

• -40 to 85°C • 1.5 to 3.6 V

±2 mBar

10 x 2 x 0.1" header

input & output Configured to operate with the Xplained Pro

development platform

MEAS MS8607

Pressure. Temperature, Humidity

• 10 to 2,000 mbar

• -40°C to 85°C

• 0 to 100% RH • 1.5 to 3.6 V

±3% RH, ±2 mBar, ±1.0°C

10 x 2 x 0.1" header input & output

Configured to operate with the Xplained Pro development platform

MEAS TSYSO1*

Temperature

• -40°C to 125°C

• 2.2 to 3.6 V

±0.1°C

10 x 2 x 0.1" header input & output

Configured to operate with the Xplained Pro development platform

MEAS TSYSO2D*

Temperature

• -40°C to 125°C

• 1.5 to 3.6 V

±0.2°C

10 x 2 x 0.1" header input & output

Configured to operate with the Xplained Pro development platform

MEAS KMA36(A)

Angular Position

• 0 to 360°

• -25°C to 85°C • 2.9 to 6.0 V

±0.1°

10 x 2 x 0.1" header input & output

Configured to operate with the Xplained Pro development platform

DRIVERS

Type

Language



MEAS HTU21D(F)

SAMD2x Microchip

FPGA Bare Metal -Linux® / Android™

PIC24x Family



ANSI C Coding



MEAS MS5637

SAMD2x Microchip PIC24x Family FPGA Bare Metal -Linux® / Android™

ANSI C Coding



MEAS MS8607

SAMD2x Microchip PIC24x Family FPGA Bare Metal -Linux® / Android™

ANSI C Coding



SAMD2x Microchip PIC24x Family



FPGA Bare Metal -Linux® / Android™

ANSI C Coding



MEAS TSYSO2D*

SAMD2x Microchip PIC24x Family FPGA Bare Metal -Linux / Android™

ANSI C Coding



MEAS KMA36(A)

SAMD2x Microchip PIC24x Family FPGA Bare Metal -Linux® / Android™

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ANSI C Coding

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